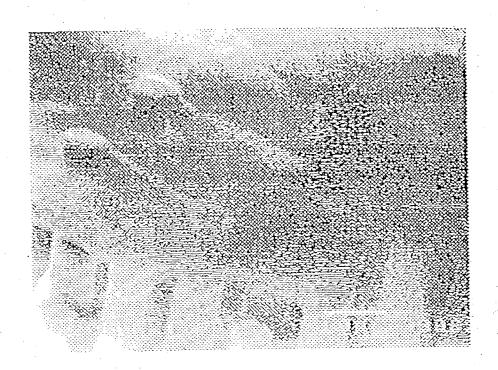
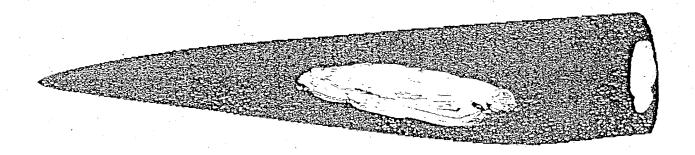
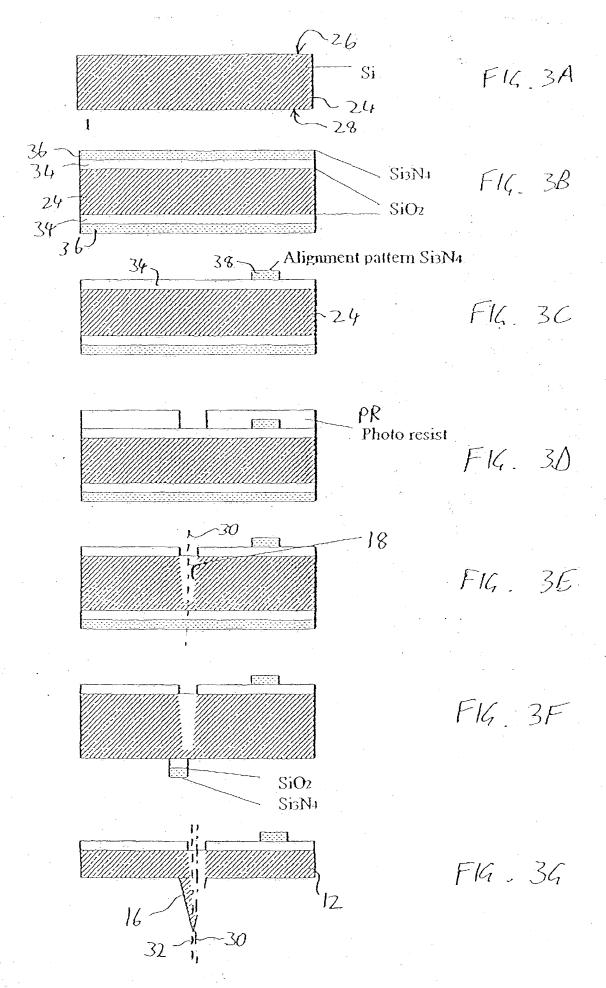
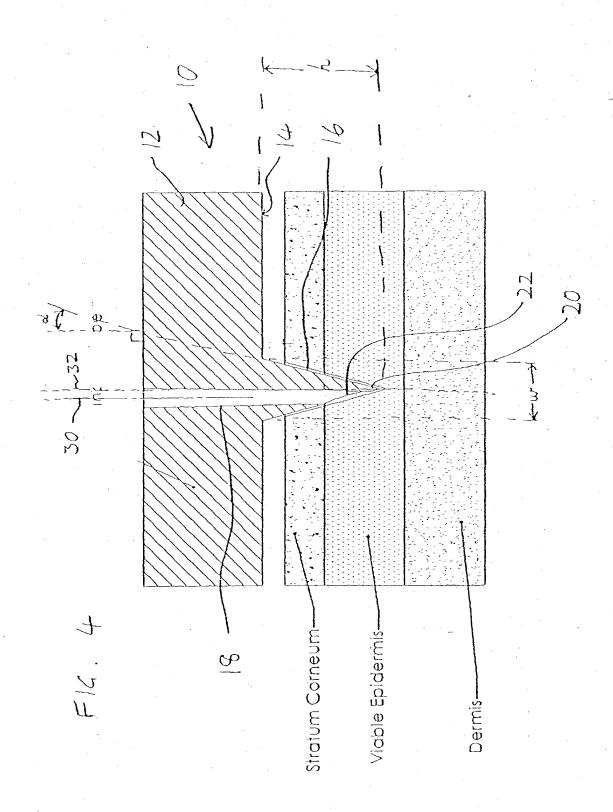
FIG. 1 (PRIOR ART)

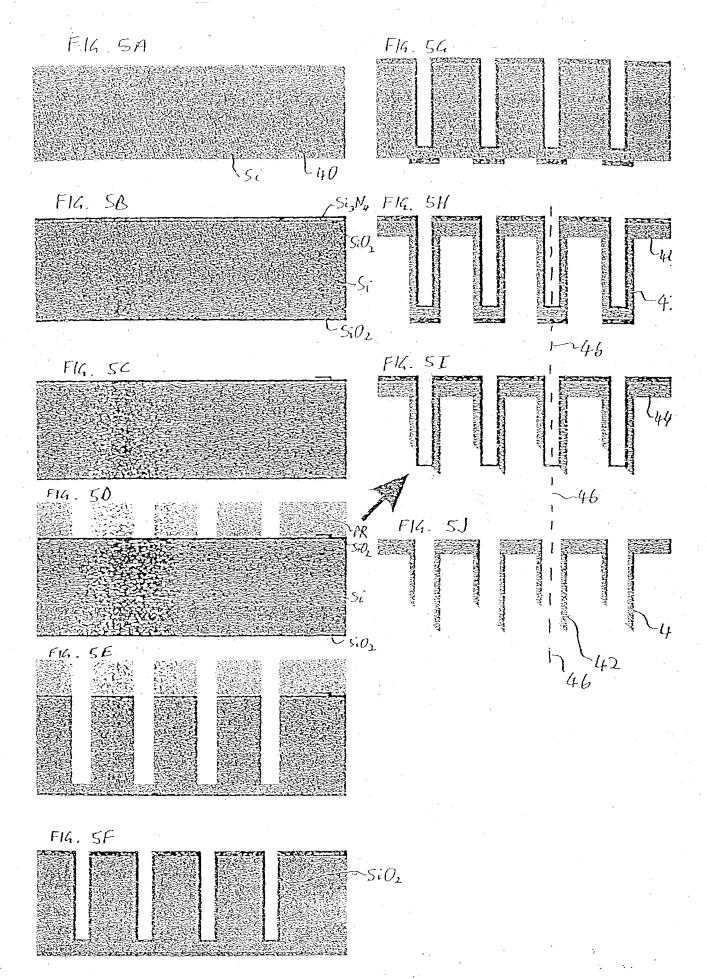


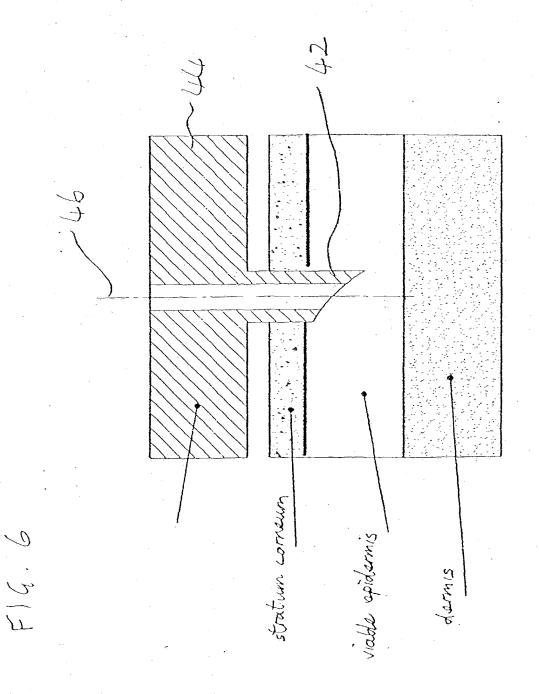
F14.2

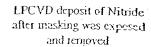






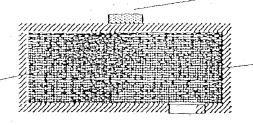






F14. 7A

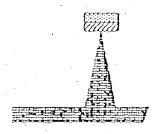
substrate



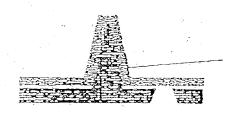
Oxidation

Etching part after masking exposed and removed

F14. 7B



F14.7C



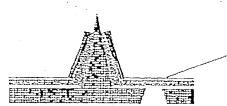
Deposit spacer layer 2 micron ef PSG

Photo resist pattern and etch base. windows

F14. 70

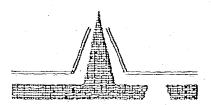


F14. 7E

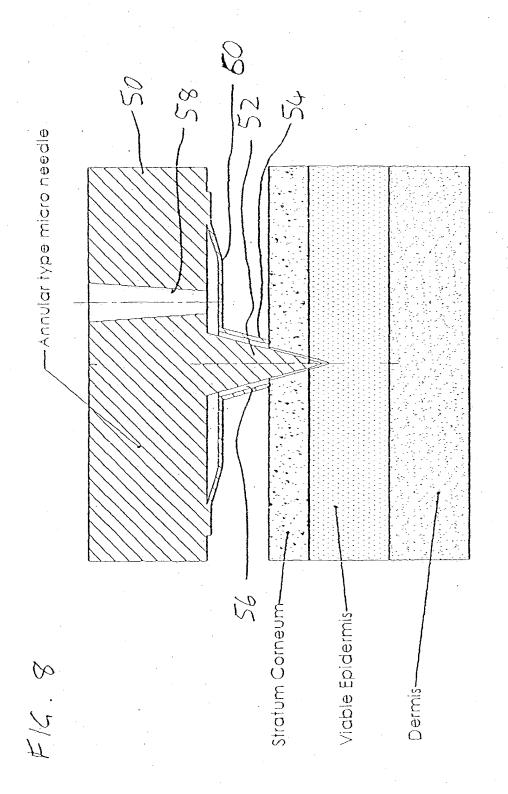


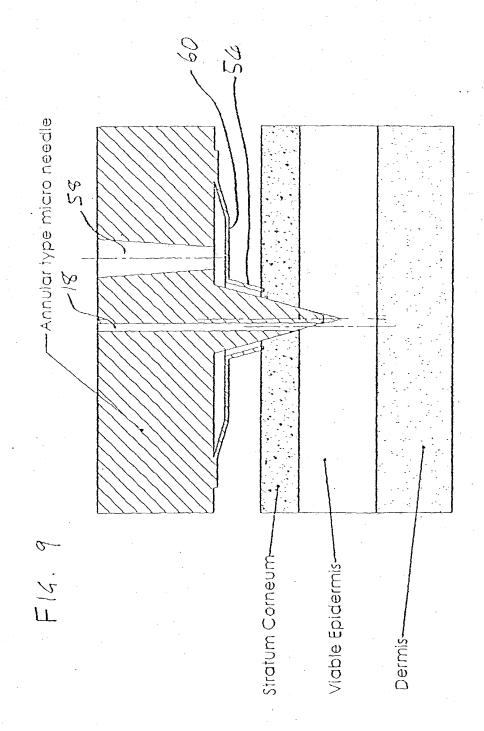
Metal coating

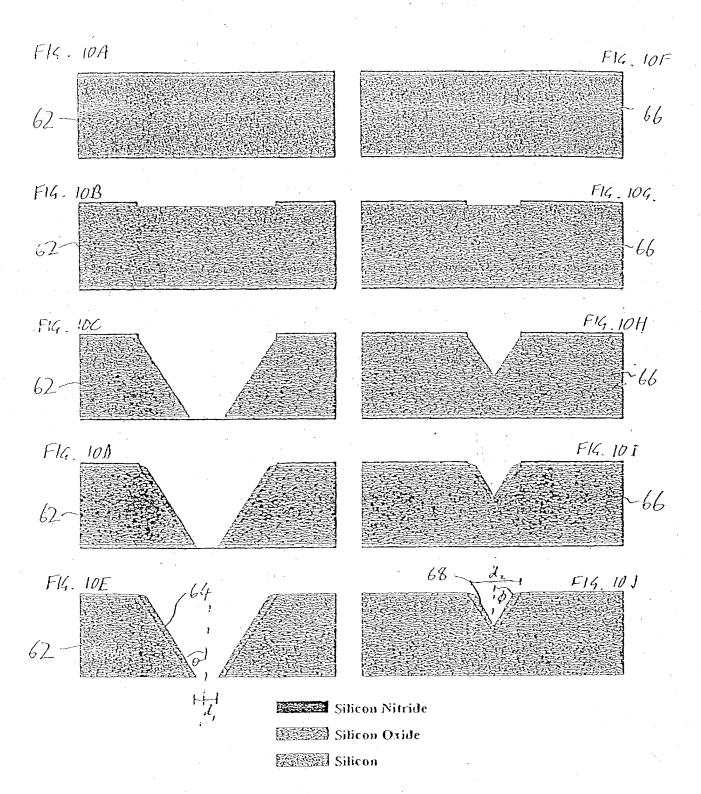
F14. 7F



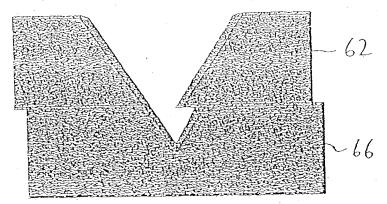
Remove resist and spacer layer



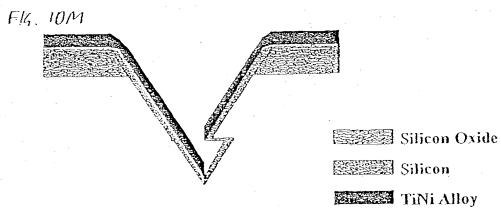


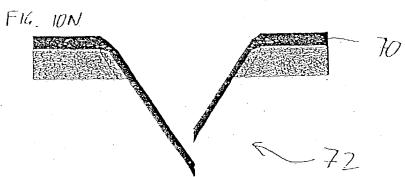


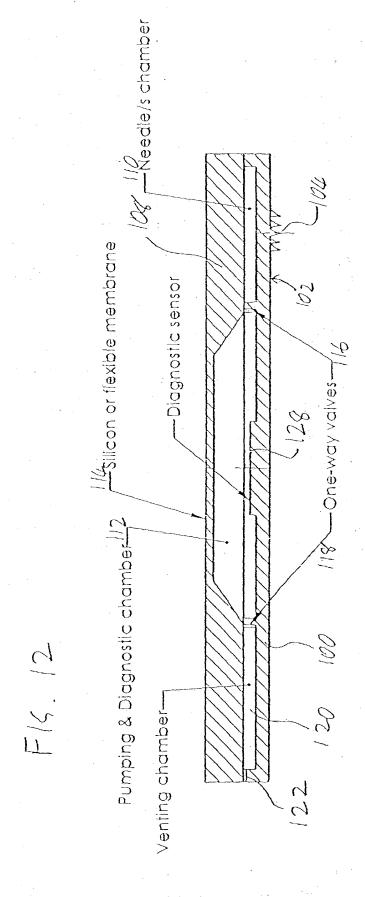
F16: 10K

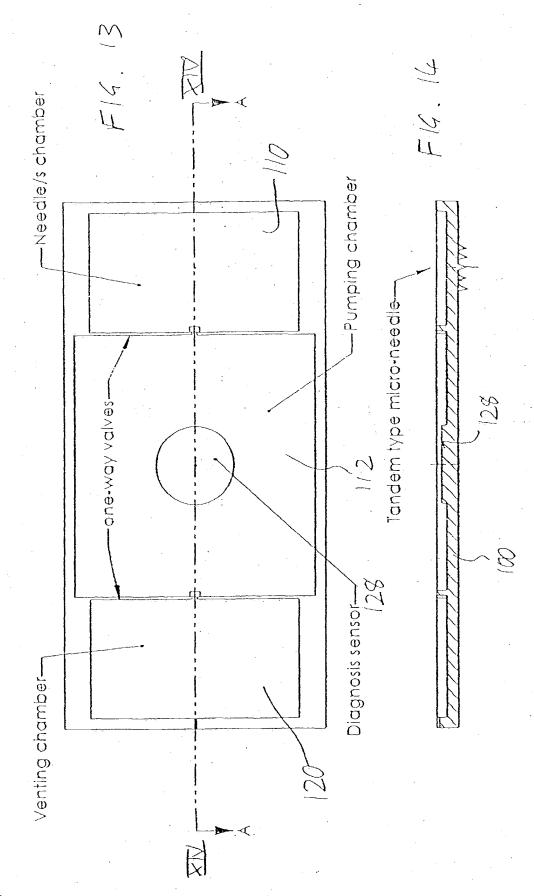


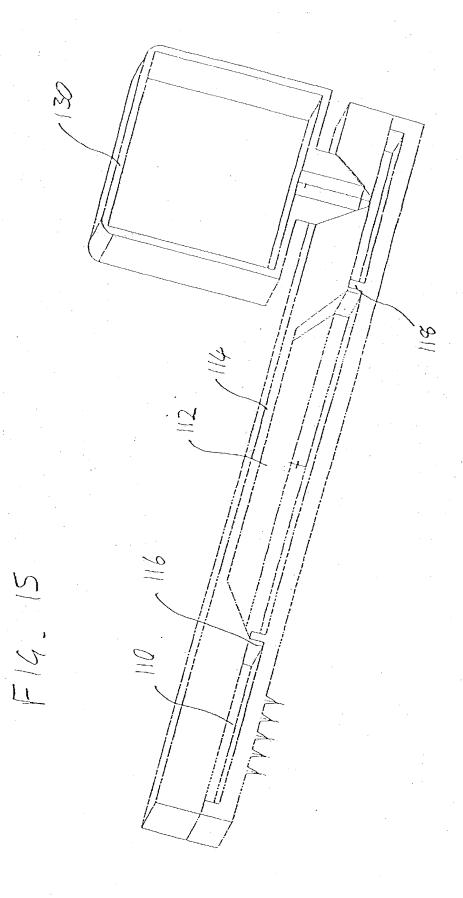
F14. 10L - 70

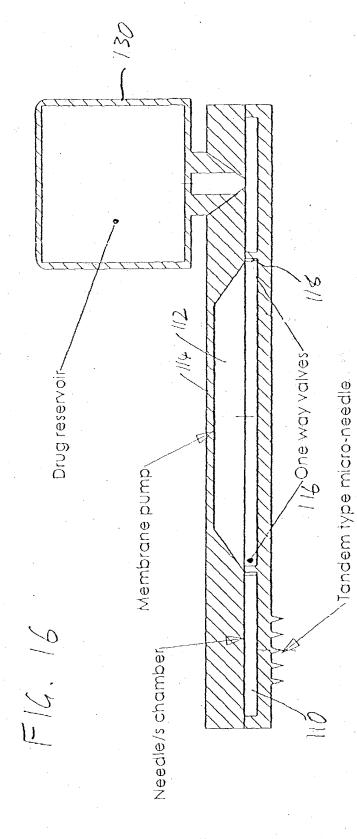


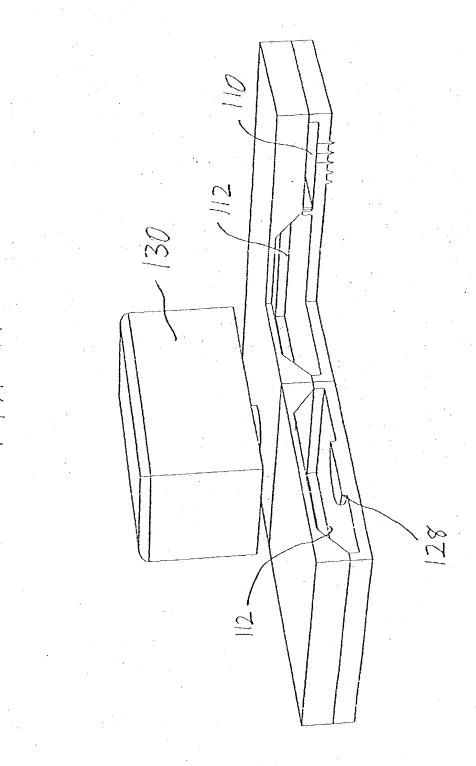


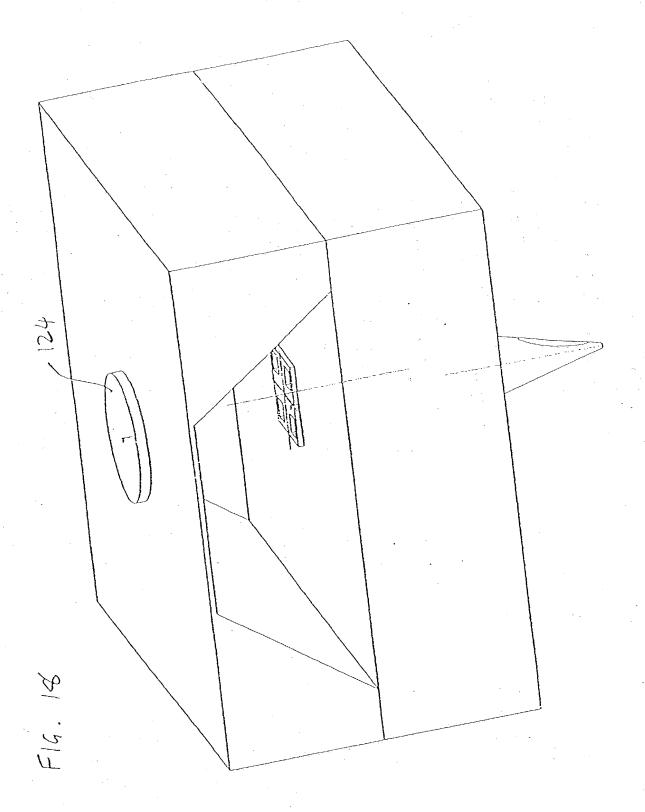


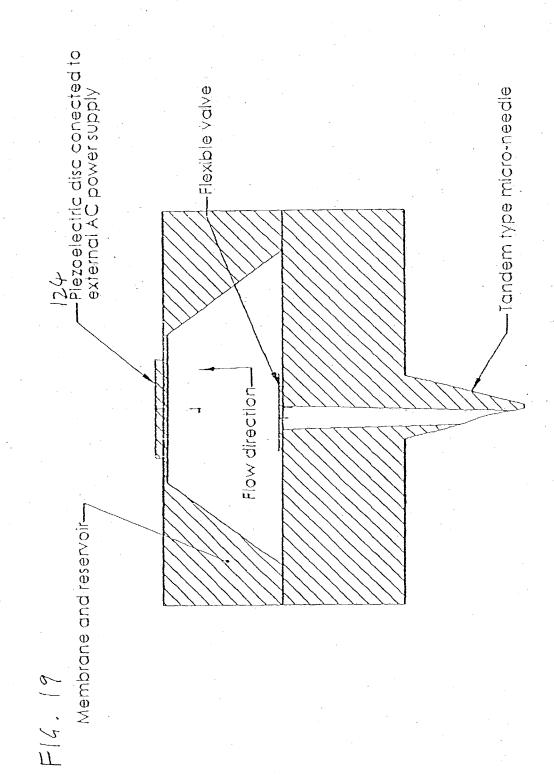


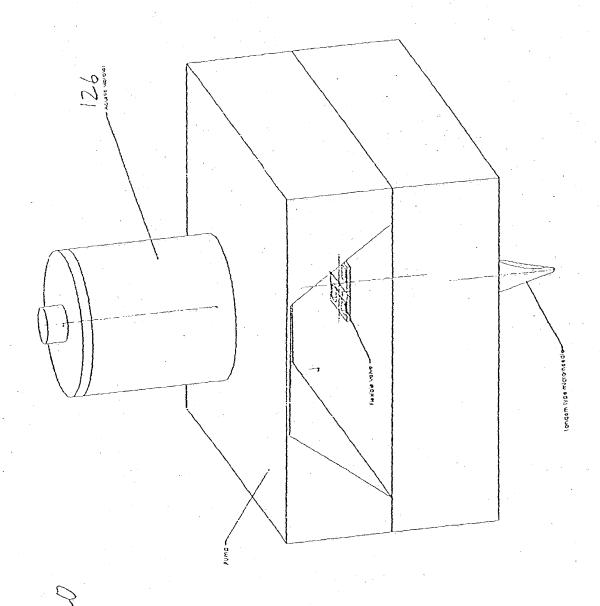




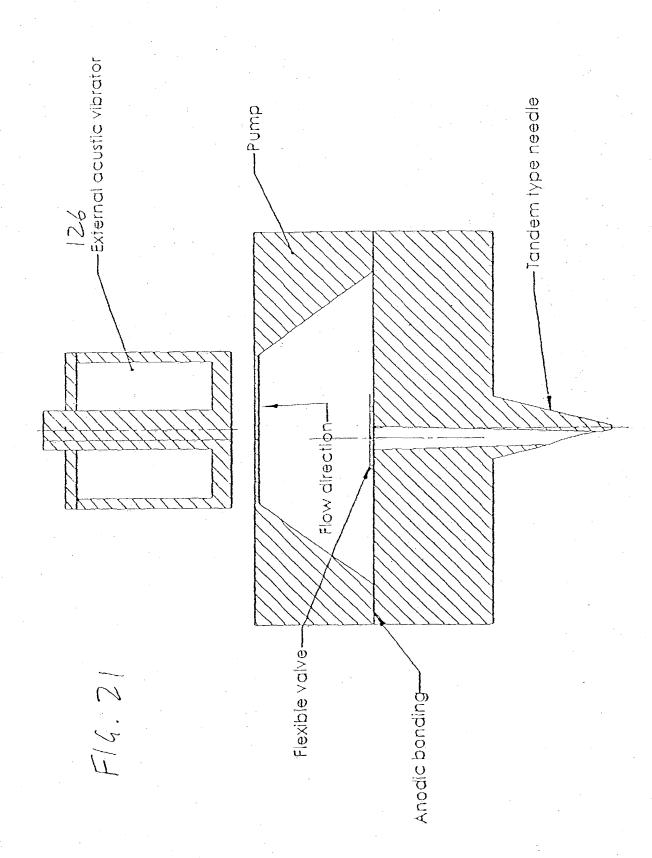


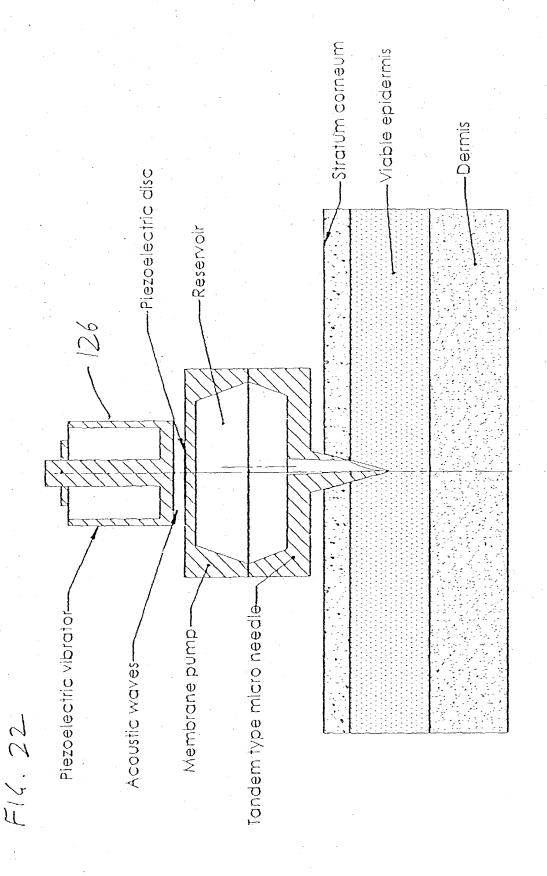






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